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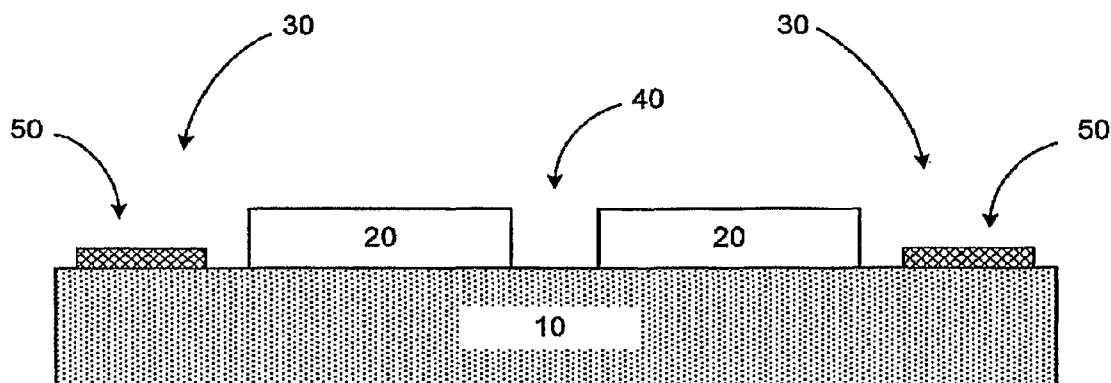
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**(54) Title:** METHODS AND MATERIALS USEFUL FOR CHIP STACKING, CHIP AND WAFER BONDING



**(57) Abstract:** Materials, and methods that use such materials, that are useful for forming chip stacks, chip and wafer bonding and wafer thinning are disclosed. Such methods and materials provide strong bonds while also being readily removed with little or no residues.